

TT4KF THRU TT4MF

GLASS PASSIVATED SURFACE MOUNT BRIDGE RECTIFIERS

Features

- ◆ Glass Passivated Chip Junction
- ◆ Reverse Voltage 800 to 1000 V
- ◆ Forward Current- 4.0 A
- High Surge Current Capability
- ◆ Designed for Surface Mount Application

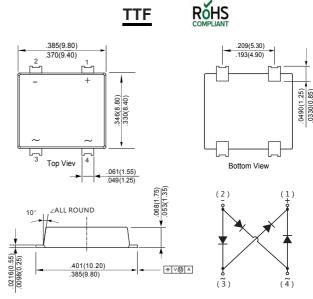
Mechanical Data

Case: JEDEC TTF molded plastic body

Terminals: Solderable per MIL-STD-750, Method 2026Á Polarity: Polarity symbol marking on body Mounting

Position: Any

Weight: 0.0163 ounce, 0.461 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	- Symbols -	TT4KF	TT4MF	Units
Marking Code		MDD TT4KF	MDD TT4MF	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	800	1000	V
Maximum RMS voltage	V_{RMS}	560	700	V
Maximum DC Blocking Voltage	V _{DC}	800	1000	V
Maximum Average Forward Rectified Current	Io	4		А
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	150		А
I ² t Rating for Fusing	I ² t	93	93	
Maximum Forward Voltage at 1.0 A	V _F		0.83 typ.	
Maximum Forward Voltage at 4.0 A	V _F	1.	1.0	
$\begin{tabular}{lllllllllllllllllllllllllllllllllll$	I _R	-	5 100	
Typical Junction Capacitance (Note1)	C _j	40		pF
Typical Thermal Resistance (Note2)	R _{0JA} R _{0JC} R _{0JL}	1	60 10 12	
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~	-55 ~ + 150	

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. P.C.B. mounted with $4\times1.5"\times1.5"$ (3.81×3.81 cm) copper pad areas.

DN:T20416A0

http://www.microdiode.com Rev:2020A0 Page :1



TT4KF THRU TT4MF

Typical Characterisitics

Fig.1 Average Rectified Output Current Derating Curve

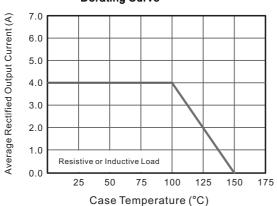


Fig.2 Typical Reverse Characteristics

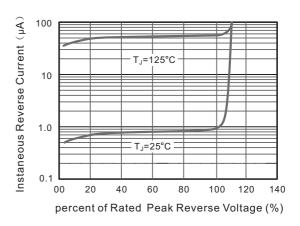


Fig.3 Typical Instaneous Forward Characteristics

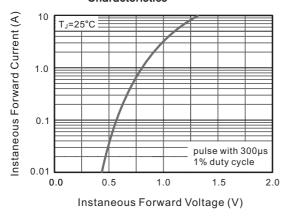


Fig.4 Typical Junction Capacitance

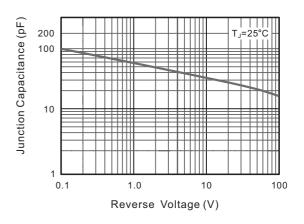


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

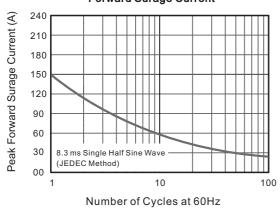
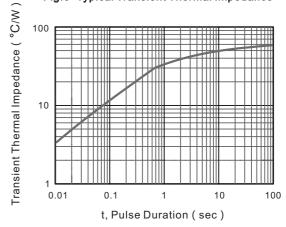


Fig.6- Typical Transient Thermal Impedance



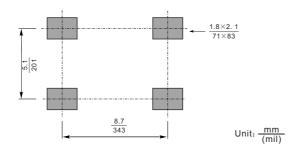
The curve above is for reference only.

http://www.microdiode.com Rev:2020A0 Page :2





Suggested Pad Layout



Note:

- 1. Controlling dimension: in/millimeters.
- 2.General tolerance: ±0.05mm.
- 3. The pad layout is for reference purposes only.

Important Notice and Disclaimer

Microdiode Electronics (Jiangsu) reserves the right to make changes to this document and its products and specifications at any time without notice. Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.

Microdiode Electronics (Jiangsu) makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, not does Microdiode Electronics (Jiangsu) assume any liability for application assistance or customer product design. Microdiode Electronics (Jiangsu) does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application.

No license is granted by implication or otherwise under any intellectual property rights of Microdiode Electronics (Jiangsu).

Microdiode Electronics (Jiangsu) products are not authorized for use as critical components in life support devices or systems without express written approval of Microdiode Electronics (Jiangsu).

http://www.microdiode.com Rev:2020A0 Page :3